

## IN THE SPECIFICATION

Please amend the paragraph beginning at page 28, prenumbered line 23, to page 29, prenumbered line 4, as follows:

Further, in the substrate processing apparatus of the present invention, a heating unit (PEB) may be mounted in interface portion B6, for example, and in the case where the time between the light exposure processing and the succeeding heating processing in the heating unit (PEB) needs to be uniform, as in the case of using a chemically amplified resist solution for example, wafer W having undergone the light exposure processing in light exposure device B7 may be transferred preferentially to the heating unit (PEB) within a prescribed period of time by delivery means 26. In this case, besides delivery means 26 in interface portion B6, a sub-transfer arm 96 dedicated to transfer via light exposure device B7 → heating unit (PEB) may be provided, as shown, e.g., in ~~Fig. 15~~ Figs. 15A and 15B.